

## PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT6605907

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
TAKASHI HATTORI	01/26/2021
YU ZHAO	01/26/2021
HIROYUKI KOBAYASHI	01/27/2021
HIROTO OTAKE	01/27/2021
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	HITACHI HIGH-TECH CORPORATION
<b>Street Address:</b>	17-1, TORANOMON 1-CHOME
<b>City:</b>	MINATO-KU, TOKYO
<b>State/Country:</b>	JAPAN
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	17276982
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(703)610-8686
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	703- 903-9000
<b>Email:</b>	mleahy@milestockbridge.com, ipdocketing@MilesStockbridge.com
<b>Correspondent Name:</b>	MILES & STOCKBRIDGE, P.C.
<b>Address Line 1:</b>	1751 PINNACLE DRIVE, SUITE 1500
<b>Address Line 4:</b>	TYSONS CORNER, VIRGINIA 22102-3833
<b>ATTORNEY DOCKET NUMBER:</b>	T3309-23962US01
<b>NAME OF SUBMITTER:</b>	MADELIENE B. LEAHY
<b>SIGNATURE:</b>	/Madeliene B. Leahy/
<b>DATE SIGNED:</b>	03/17/2021
<b>Total Attachments: 2</b>	
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**ASSIGNMENT**  
( 譲 渡 証 )

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me by Hitachi High-Tech Corporation, a corporation organized under the laws of Japan, located at 17-1, Toranomom 1-chome, Minato-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi High-Tech Corporation, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

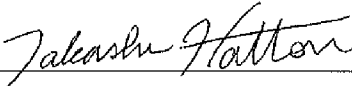
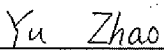
**ETCHING METHOD**

Invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi High-Tech Corporation, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi High-Tech Corporation,

Signed on the date(s) indicated aside signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u>Takashi HATTORI</u> 	<u>1/26/2021</u>
2) <u>Yu ZHAO</u> 	<u>1/26/2021</u>
3) <u>Hiroyuki KOBAYASHI</u>	_____
4) <u>Hiroto OTAKE</u>	_____
5) _____	_____
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____

( 譲渡証 )

As a below named inventor, I hereby declare that:

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invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi High-Tech Corporation, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi High-Tech Corporation,

Signed on the date(s) indicated aside signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) Takashi HATTORI	
2) Yu ZHAO	
3) Hiroyuki KOBAYASHI <i>Hiroyuki Kobayashi</i>	1/27/2021
4) Hiroto OTAKE <i>Hiroto Otake</i>	1/27/2021
5)	
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10)	